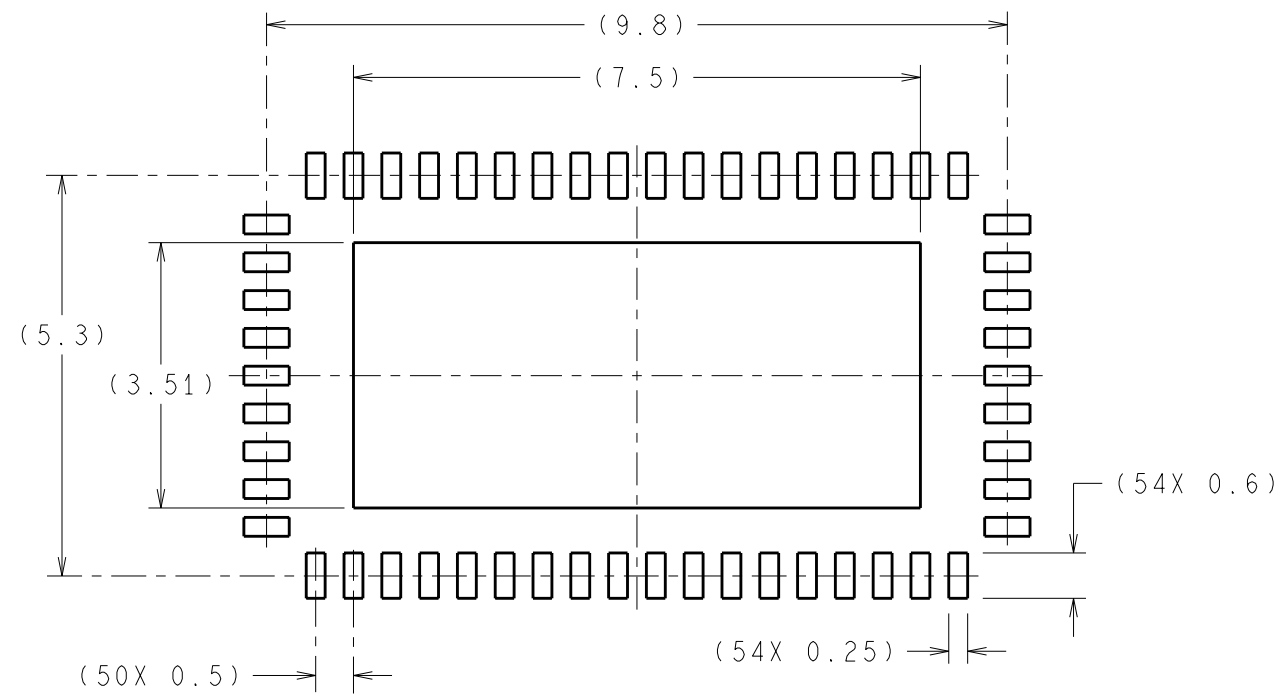
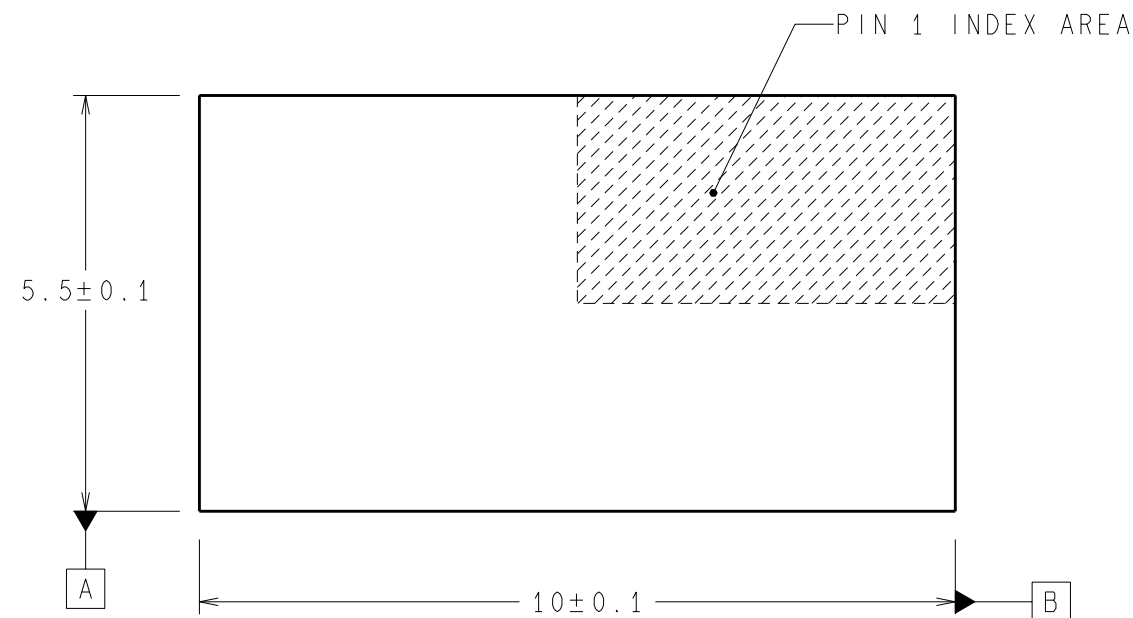


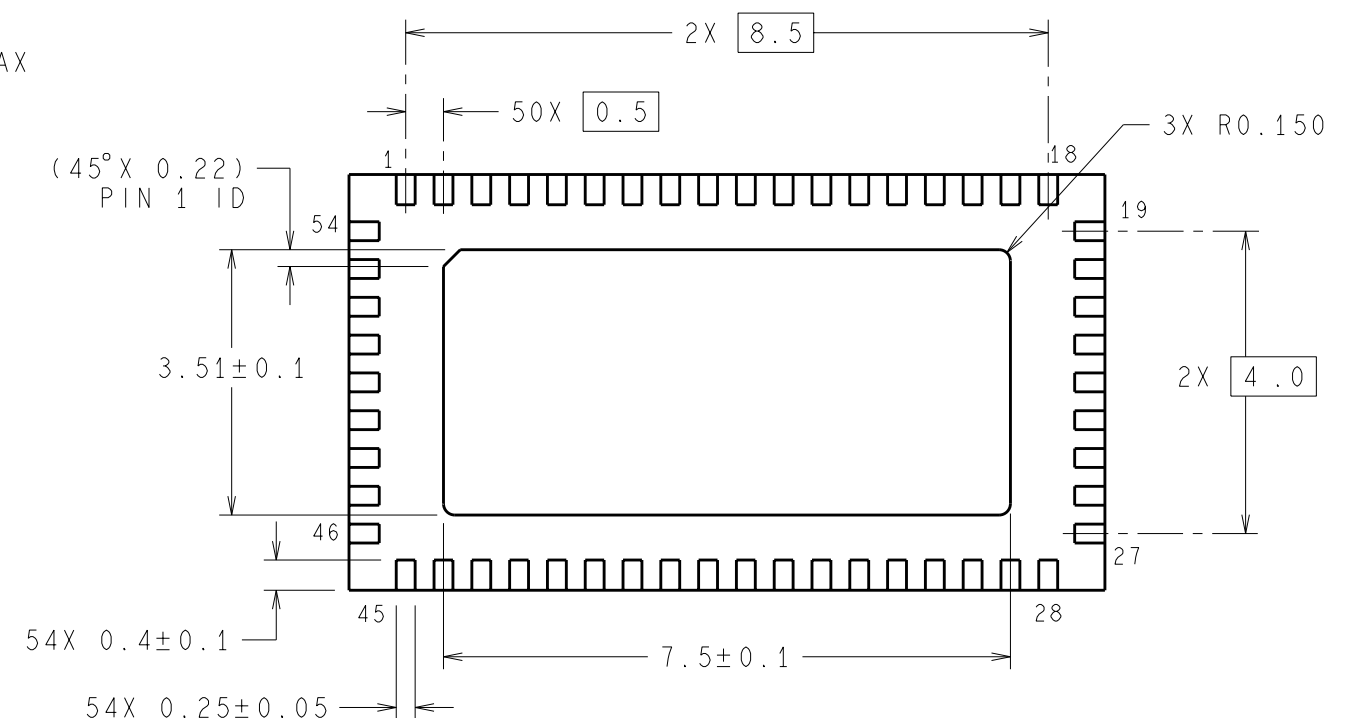
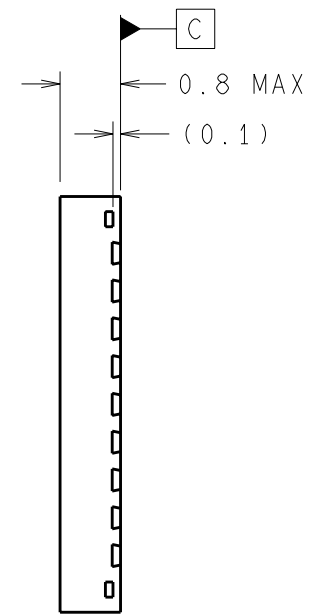
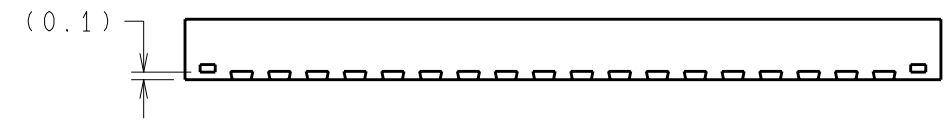
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	2529	06/05/2008	TKY/TL/EL
B	CHANGE DAP SIZE TO 7.5x3.51mm FROM 8.3x3.8mm	2659	01/06/2009	TKY/TL/TKY



RECOMMENDED LAND PATTERN



DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN () FOR REFERENCE ONLY



⊕	0.1	M	C	A	⊙	B	⊙
	0.05	M	C				

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL WEB (www.national.com).
- MAXIMUM ALLOWABLE METAL BURR ON LEAD TIPS AT THE PACKAGE EDGES IS 76 MICRONS.
- NO JEDEC REGISTRATION AS OF JANUARY 2009.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	LLP, QUAD, 10x5.5x0.8mm, 54 LD, 0.5mm PITCH, NO LEAD PULLBACK
DRAWN	TK YII & TLEQUANG	06/05/2008		
DFTG. CHK.	THANH LEQUANG	01/06/2009		
ENGR. CHK.	TK YII	01/06/2009		
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
 MM	NTS	B	(SC)MKT-SQA54A	B
FORMERLY: N/A			SHEET 1 of 1	